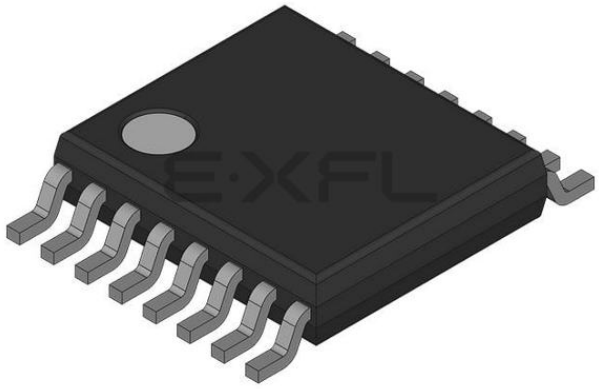

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	-
Peripherals	LVD, POR, PWM
Number of I/O	13
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	16-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	16-TSSOP
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc68hc908qy4mdt

The following revision history table summarizes changes contained in this document. For your convenience, the page number designators have been linked to the appropriate location.

Revision History (Sheet 1 of 3)

Date	Revision Level	Description	Page Number(s)
September, 2002	N/A	Initial release	N/A
December, 2002	0.1	1.2 Features — Added 8-pin dual flat no lead (DFN) packages to features list.	19
		Figure 1-2. MCU Pin Assignments — Figure updated to include DFN packages.	21
		Figure 2-1. Memory Map — Clarified illegal address and unimplemented memory.	27
		Figure 2-2. Control, Status, and Data Registers — Corrected bit definitions for Port A Data Register (PTA) and Data Direction Register A (DDRA).	27
		Table 13-3. Interrupt Sources — Corrected vector addresses for keyboard interrupt and ADC conversion complete interrupt.	118
		Chapter 13 System Integration Module (SIM) — Removed reference to break status register as it is duplicated in break module.	113
		11.3.1 Internal Oscillator and 11.3.1.1 Internal Oscillator Trimming — Clarified oscillator trim option ordering information and what to expect with untrimmed device.	92
		Figure 11-5. Oscillator Trim Register (OSCTRIM) — Bit 1 designation corrected.	98
		Figure 15-13. Monitor Mode Circuit (Internal Clock, No High Voltage) — Diagram updated for clarity.	150
		Figure 12-1. I/O Port Register Summary — Corrected bit definitions for PTA7, DDRA7, and DDRA6.	99
		Figure 12-2. Port A Data Register (PTA) — Corrected bit definition for PTA7.	100
		Figure 12-3. Data Direction Register A (DDRA) — Corrected bit definitions for DDRA7 and DDRA6.	101
		Figure 12-6. Port B Data Register (PTB) — Corrected bit definition for PTB1	103
		Chapter 9 Keyboard Interrupt Module (KBI) — Section reworked after deletion of auto wakeup for clarity.	83
		Chapter 4 Auto Wakeup Module (AWU) — New section added for clarity.	49
		Figure 10-1. LVI Module Block Diagram — Corrected LVI stop representation.	87
		Chapter 16 Electrical Specifications — Extensive changes made to electrical specifications.	169
		17.5 8-Pin Dual Flat No Lead (DFN) Package (Case #1452) — Added case outline drawing for DFN package.	177
		Chapter 17 Ordering Information and Mechanical Specifications — Added ordering information for DFN package.	185
January, 2003	0.2	4.2 Features — Corrected third bulleted item.	49

1.5 Pin Functions

Table 1-2 provides a description of the pin functions.

Table 1-2. Pin Functions

Pin Name	Description	Input/Output
V_{DD}	Power supply	Power
V_{SS}	Power supply ground	Power
PTA0	PTA0 — General purpose I/O port	Input/Output
	AD0 — A/D channel 0 input	Input
	TCH0 — Timer Channel 0 I/O	Input/Output
	KBI0 — Keyboard interrupt input 0	Input
PTA1	PTA1 — General purpose I/O port	Input/Output
	AD1 — A/D channel 1 input	Input
	TCH1 — Timer Channel 1 I/O	Input/Output
	KBI1 — Keyboard interrupt input 1	Input
PTA2	PTA2 — General purpose input-only port	Input
	$\overline{IRQ}$ — External interrupt with programmable pullup and Schmitt trigger input	Input
	KBI2 — Keyboard interrupt input 2	Input
	TCLK — Timer clock input	Input
PTA3	PTA3 — General purpose I/O port	Input/Output
	$\overline{RST}$ — Reset input, active low with internal pullup and Schmitt trigger	Input
	KBI3 — Keyboard interrupt input 3	Input
PTA4	PTA4 — General purpose I/O port	Input/Output
	OSC2 —XTAL oscillator output (XTAL option only) RC or internal oscillator output (OSC2EN = 1 in PTAPUE register)	Output Output
	AD2 — A/D channel 2 input	Input
	KBI4 — Keyboard interrupt input 4	Input
PTA5	PTA5 — General purpose I/O port	Input/Output
	OSC1 — XTAL, RC, or external oscillator input	Input
	AD3 — A/D channel 3 input	Input
	KBI5 — Keyboard interrupt input 5	Input
PTB[0:7](1)	8 general-purpose I/O ports	Input/Output

1. The PTB pins are not available on the 8-pin packages (see note in 12.1 Introduction).

2.4 Input/Output (I/O) Section

Addresses $0000–$003F, shown in Figure 2-2, contain most of the control, status, and data registers. Additional I/O registers have these addresses:

- $FE00 — Break status register, BSR
- $FE01 — Reset status register, SRSR
- $FE02 — Break auxiliary register, BRKAR
- $FE03 — Break flag control register, BFCR
- $FE04 — Interrupt status register 1, INT1
- $FE05 — Interrupt status register 2, INT2
- $FE06 — Interrupt status register 3, INT3
- $FE07 — Reserved
- $FE08 — FLASH control register, FLCR
- $FE09 — Break address register high, BRKH
- $FE0A — Break address register low, BRKL
- $FE0B — Break status and control register, BRKSCR
- $FE0C — LVI status register, LVISR
- $FE0D — Reserved
- $FFBE — FLASH block protect register, FLBPR
- $FFC0 — Internal OSC trim value (factory programmed, VDD = 5.0 V)
- $FFC1 — Internal OSC trim value (factory programmed, VDD = 3.0 V)
- $FFFF — COP control register, COPCTL

Addr.	Register Name		Bit 7	6	5	4	3	2	1	Bit 0
$0000	Port A Data Register (PTA) See page 98.	Read:	R	AWUL	PTA5	PTA4	PTA3	PTA2	PTA1	PTA0
		Write:								
		Reset:	Unaffected by reset							
$0001	Port B Data Register (PTB) See page 100.	Read:	PTB7	PTB6	PTB5	PTB4	PTB3	PTB2	PTB1	PTB0
		Write:								
		Reset:	Unaffected by reset							
$0002	Unimplemented									
$0003	Unimplemented									
$0004	Data Direction Register A (DDRA) See page 98.	Read:	R	R	DDRA5	DDRA4	DDRA3	0	DDRA1	DDRA0
		Write:								
		Reset:	0	0	0	0	0	0	0	0
$0005	Data Direction Register B (DDRB) See page 101.	Read:	DDRB7	DDRB6	DDRB5	DDRB4	DDRB3	DDRB2	DDRB1	DDRB0
		Write:								
		Reset:	0	0	0	0	0	0	0	0

= Unimplemented R = Reserved U = Unaffected

Figure 2-2. Control, Status, and Data Registers (Sheet 1 of 5)

Table 2-1. Vector Addresses

Vector Priority	Vector	Address	Vector
Lowest ↑	IF15	$FFDE	ADC conversion complete vector (high)
		$FFDF	ADC conversion complete vector (low)
	IF14	$FFE0	Keyboard vector (high)
		$FFE1	Keyboard vector (low)
	IF13 ↓ IF6	—	Not used
	IF5	$FFF2	TIM overflow vector (high)
		$FFF3	TIM overflow vector (low)
	IF4	$FFF4	TIM Channel 1 vector (high)
		$FFF5	TIM Channel 1 vector (low)
	IF3	$FFF6	TIM Channel 0 vector (high)
		$FFF7	TIM Channel 0 vector (low)
	IF2	—	Not used
	IF1	$FFFA	$\overline{\text{IRQ}}$ vector (high)
		$FFFB	$\overline{\text{IRQ}}$ vector (low)
	—	$FFFC	SWI vector (high)
		$FFFD	SWI vector (low)
	—	$FFFE	Reset vector (high)
Highest		$FFFF	Reset vector (low)

2.5 Random-Access Memory (RAM)

Addresses $0080–$00FF are RAM locations. The location of the stack RAM is programmable. The 16-bit stack pointer allows the stack to be anywhere in the 64-Kbyte memory space.

NOTE

For correct operation, the stack pointer must point only to RAM locations.

Before processing an interrupt, the central processor unit (CPU) uses five bytes of the stack to save the contents of the CPU registers.

NOTE

For M6805, M146805, and M68HC05 compatibility, the H register is not stacked.

During a subroutine call, the CPU uses two bytes of the stack to store the return address. The stack pointer decrements during pushes and increments during pulls.

NOTE

Be careful when using nested subroutines. The CPU may overwrite data in the RAM during a subroutine or during the interrupt stacking operation.

ERASE — Erase Control Bit

This read/write bit configures the memory for erase operation. ERASE is interlocked with the PGM bit such that both bits cannot be equal to 1 or set to 1 at the same time.

1 = Erase operation selected
0 = Erase operation unselected

PGM — Program Control Bit

This read/write bit configures the memory for program operation. PGM is interlocked with the ERASE bit such that both bits cannot be equal to 1 or set to 1 at the same time.

1 = Program operation selected
0 = Program operation unselected

2.6.2 FLASH Page Erase Operation

Use the following procedure to erase a page of FLASH memory. A page consists of 64 consecutive bytes starting from addresses $XX00, $XX40, $XX80, or $XXC0. The 48-byte user interrupt vectors area also forms a page. Any FLASH memory page can be erased alone.

1. Set the ERASE bit and clear the MASS bit in the FLASH control register.
2. Read the FLASH block protect register.
3. Write any data to any FLASH location within the address range of the block to be erased.
4. Wait for a time, t_{NVS} (minimum 10 μs).
5. Set the HVEN bit.
6. Wait for a time, t_{Erase} (minimum 1 ms or 4 ms).
7. Clear the ERASE bit.
8. Wait for a time, t_{NVH} (minimum 5 μs).
9. Clear the HVEN bit.
10. After time, t_{RCV} (typical 1 μs), the memory can be accessed in read mode again.

NOTE

Programming and erasing of FLASH locations cannot be performed by code being executed from the FLASH memory. While these operations must be performed in the order as shown, but other unrelated operations may occur between the steps.

CAUTION

A page erase of the vector page will erase the internal oscillator trim values at $FFC0 and $FFC1.

In applications that require more than 1000 program/erase cycles, use the 4 ms page erase specification to get improved long-term reliability. Any application can use this 4 ms page erase specification. However, in applications where a FLASH location will be erased and reprogrammed less than 1000 times, and speed is important, use the 1 ms page erase specification to get a shorter cycle time.

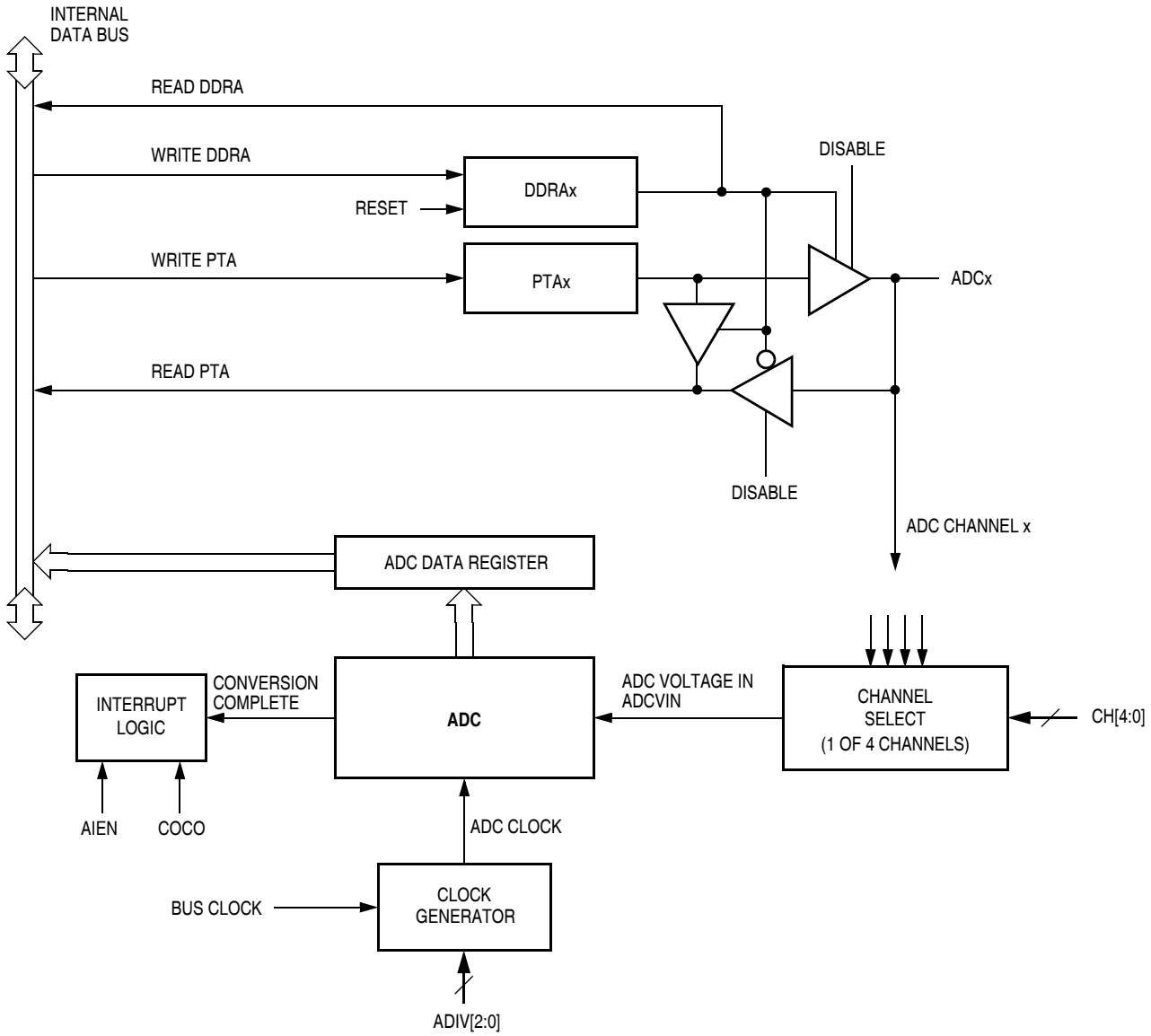


Figure 3-2. ADC Block Diagram

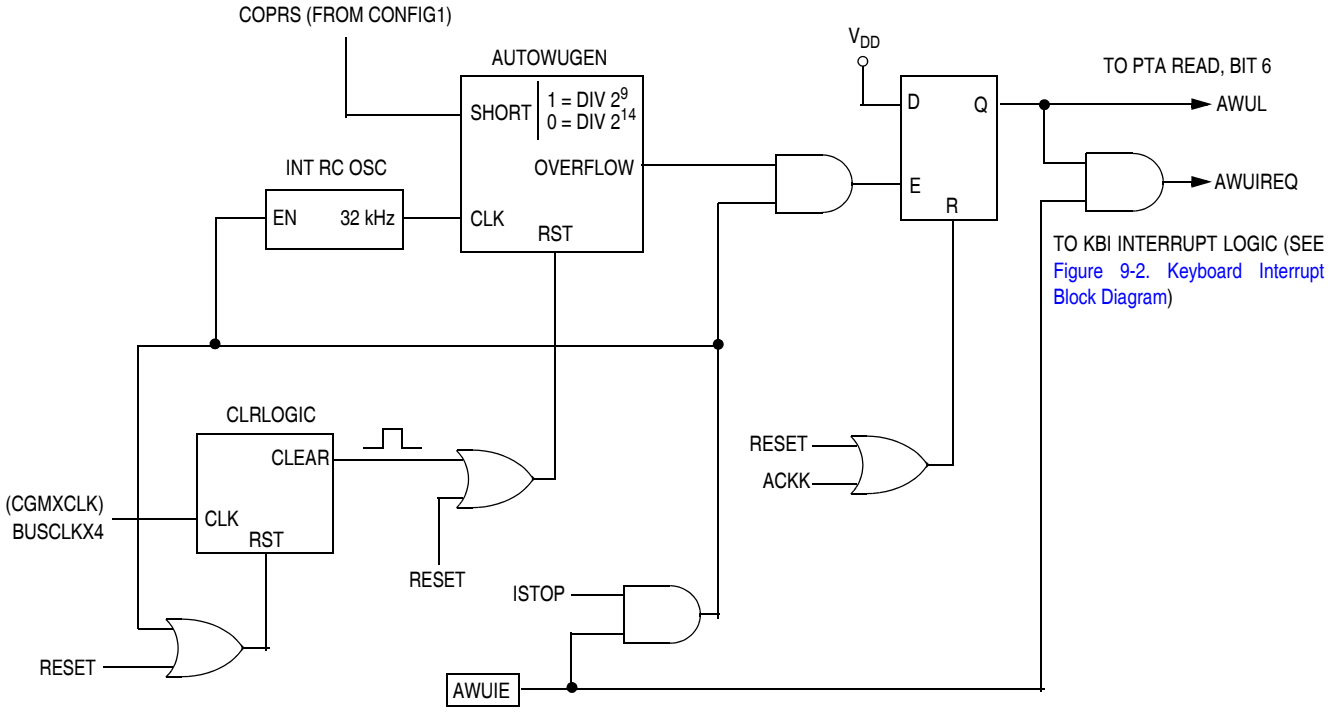


Figure 4-1. Auto Wakeup Interrupt Request Generation Logic

The auto wakeup RC oscillator is highly dependent on operating voltage and temperature. This feature is not recommended for use as a time-keeping function.

The wakeup request is latched to allow the interrupt source identification. The latched value, AWUL, can be read directly from the bit 6 position of PTA data register. This is a read-only bit which is occupying an empty bit position on PTA. No PTA associated registers, such as PTA6 data, PTA6 direction, and PTA6 pullup exist for this bit. The latch can be cleared by writing to the ACKK bit in the KBSCR register. Reset also clears the latch. AWUIE bit in KBI interrupt enable register (see Figure 4-1) has no effect on AWUL reading.

The AWU oscillator and counters are inactive in normal operating mode and become active only upon entering stop mode.

4.4 Wait Mode

The AWU module remains inactive in wait mode.

4.5 Stop Mode

When the AWU module is enabled (AWUIE = 1 in the keyboard interrupt enable register) it is activated automatically upon entering stop mode. Clearing the IMASKK bit in the keyboard status and control register enables keyboard interrupt requests to bring the MCU out of stop mode. The AWU counters start from ‘0’ each time stop mode is entered.

Chapter 7
Central Processor Unit (CPU)

7.1 Introduction

The M68HC08 CPU (central processor unit) is an enhanced and fully object-code-compatible version of the M68HC05 CPU. The *CPU08 Reference Manual* (document order number CPU08RM/AD) contains a description of the CPU instruction set, addressing modes, and architecture.

7.2 Features

Features of the CPU include:

- Object code fully upward-compatible with M68HC05 Family
- 16-bit stack pointer with stack manipulation instructions
- 16-bit index register with x-register manipulation instructions
- 8-MHz CPU internal bus frequency
- 64-Kbyte program/data memory space
- 16 addressing modes
- Memory-to-memory data moves without using accumulator
- Fast 8-bit by 8-bit multiply and 16-bit by 8-bit divide instructions
- Enhanced binary-coded decimal (BCD) data handling
- Modular architecture with expandable internal bus definition for extension of addressing range beyond 64 Kbytes
- Low-power stop and wait modes

7.3 CPU Registers

Figure 7-1 shows the five CPU registers. CPU registers are not part of the memory map.

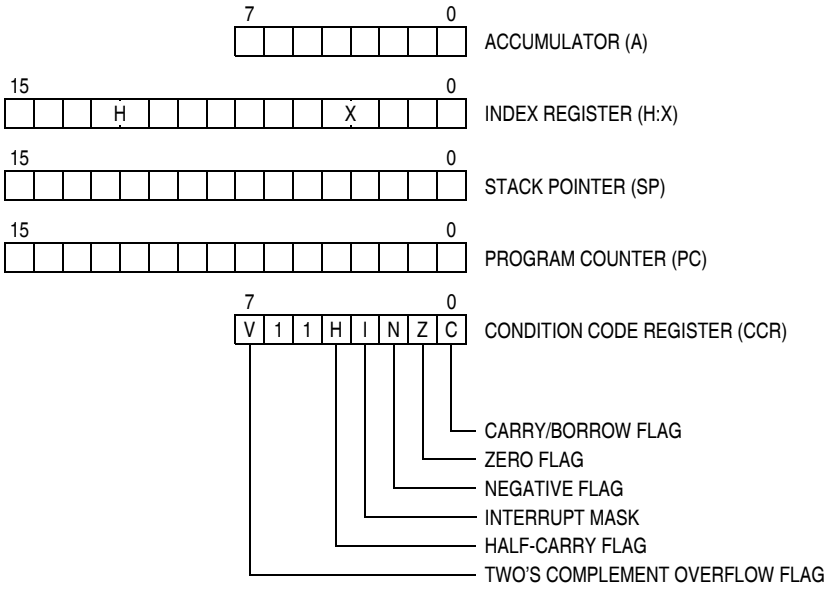


Figure 7-1. CPU Registers

7.3.1 Accumulator

The accumulator is a general-purpose 8-bit register. The CPU uses the accumulator to hold operands and the results of arithmetic/logic operations.

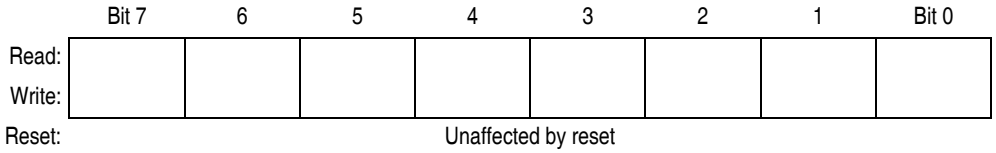


Figure 7-2. Accumulator (A)

7.3.2 Index Register

The 16-bit index register allows indexed addressing of a 64-Kbyte memory space. H is the upper byte of the index register, and X is the lower byte. H:X is the concatenated 16-bit index register.

In the indexed addressing modes, the CPU uses the contents of the index register to determine the conditional address of the operand.

The index register can serve also as a temporary data storage location.

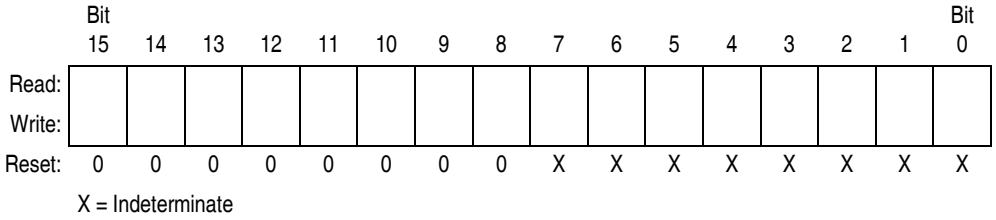


Figure 7-3. Index Register (H:X)

12.3.2 Data Direction Register B

Data direction register B (DDRB) determines whether each port B pin is an input or an output. Writing a 1 to a DDRB bit enables the output buffer for the corresponding port B pin; a 0 disables the output buffer.

Address: $0005

	Bit 7	6	5	4	3	2	1	Bit 0
Read: Write:	DDRB7	DDRB6	DDRB5	DDRB4	DDRB3	DDRB2	DDRB1	DDRB0
Reset:	0	0	0	0	0	0	0	0

Figure 12-6. Data Direction Register B (DDRB)

DDRB[7:0] — Data Direction Register B Bits

These read/write bits control port B data direction. Reset clears DDRB[7:0], configuring all port B pins as inputs.

1 = Corresponding port B pin configured as output
0 = Corresponding port B pin configured as input

NOTE

Avoid glitches on port B pins by writing to the port B data register before changing data direction register B bits from 0 to 1. Figure 12-7 shows the port B I/O logic.

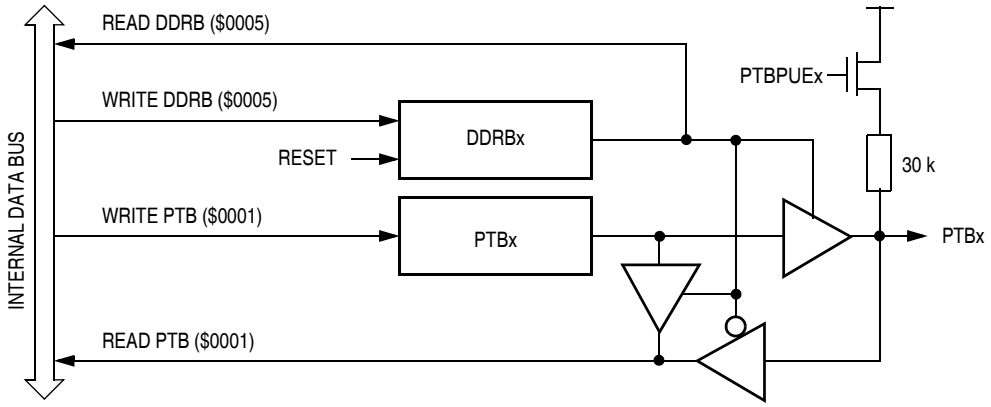


Figure 12-7. Port B I/O Circuit

When DDRBx is a 1, reading address $0001 reads the PTBx data latch. When DDRBx is a 0, reading address $0001 reads the voltage level on the pin. The data latch can always be written, regardless of the state of its data direction bit. Table 12-2 summarizes the operation of the port B pins.

Table 12-2. Port B Pin Functions

DDRB Bit	PTB Bit	I/O Pin Mode	Accesses to DDRB	Accesses to PTB	
			Read/Write	Read	Write
0	X(1)	Input, Hi-Z(2)	DDRB7–DDRB0	Pin	PTB7–PTB0(3)
1	X	Output	DDRB7–DDRB0	Pin	PTB7–PTB0

1. X = don't care
2. Hi-Z = high impedance
3. Writing affects data register, but does not affect the input.

13.4.1 External Pin Reset

The $\overline{RST}$ pin circuits include an internal pullup device. Pulling the asynchronous $\overline{RST}$ pin low halts all processing. The PIN bit of the SIM reset status register (SRSR) is set as long as $\overline{RST}$ is held low for at least the minimum t_{RL} time. Figure 13-3 shows the relative timing. The $\overline{RST}$ pin function is only available if the RSTEN bit is set in the CONFIG2 register.

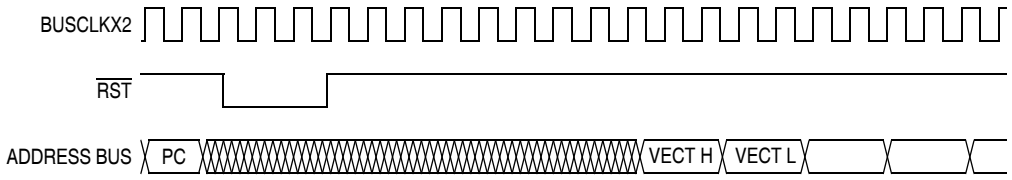


Figure 13-3. External Reset Timing

13.4.2 Active Resets from Internal Sources

The $\overline{RST}$ pin is initially setup as a general-purpose input after a POR. Setting the RSTEN bit in the CONFIG2 register enables the pin for the reset function. This section assumes the RSTEN bit is set when describing activity on the $\overline{RST}$ pin.

NOTE

For POR and LVI resets, the SIM cycles through 4096 BUSCLKX4 cycles during which the SIM forces the $\overline{RST}$ pin low. The internal reset signal then follows the sequence from the falling edge of $\overline{RST}$ shown in Figure 13-4.

The COP reset is asynchronous to the bus clock.

The active reset feature allows the part to issue a reset to peripherals and other chips within a system built around the MCU.

All internal reset sources actively pull the $\overline{RST}$ pin low for 32 BUSCLKX4 cycles to allow resetting of external peripherals. The internal reset signal IRST continues to be asserted for an additional 32 cycles (see Figure 13-4). An internal reset can be caused by an illegal address, illegal opcode, COP time out, LVI, or POR (see Figure 13-5).

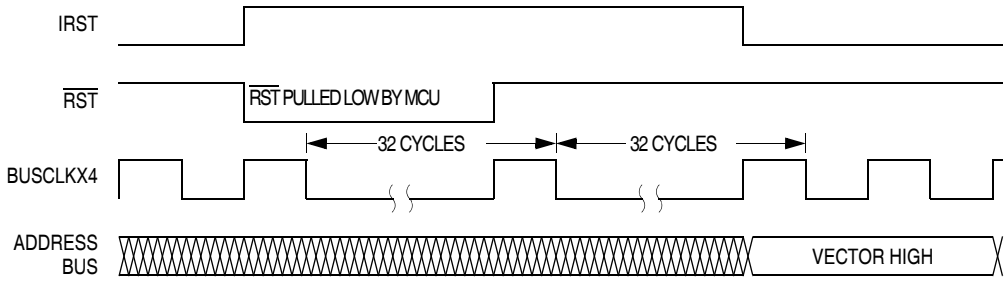


Figure 13-4. Internal Reset Timing

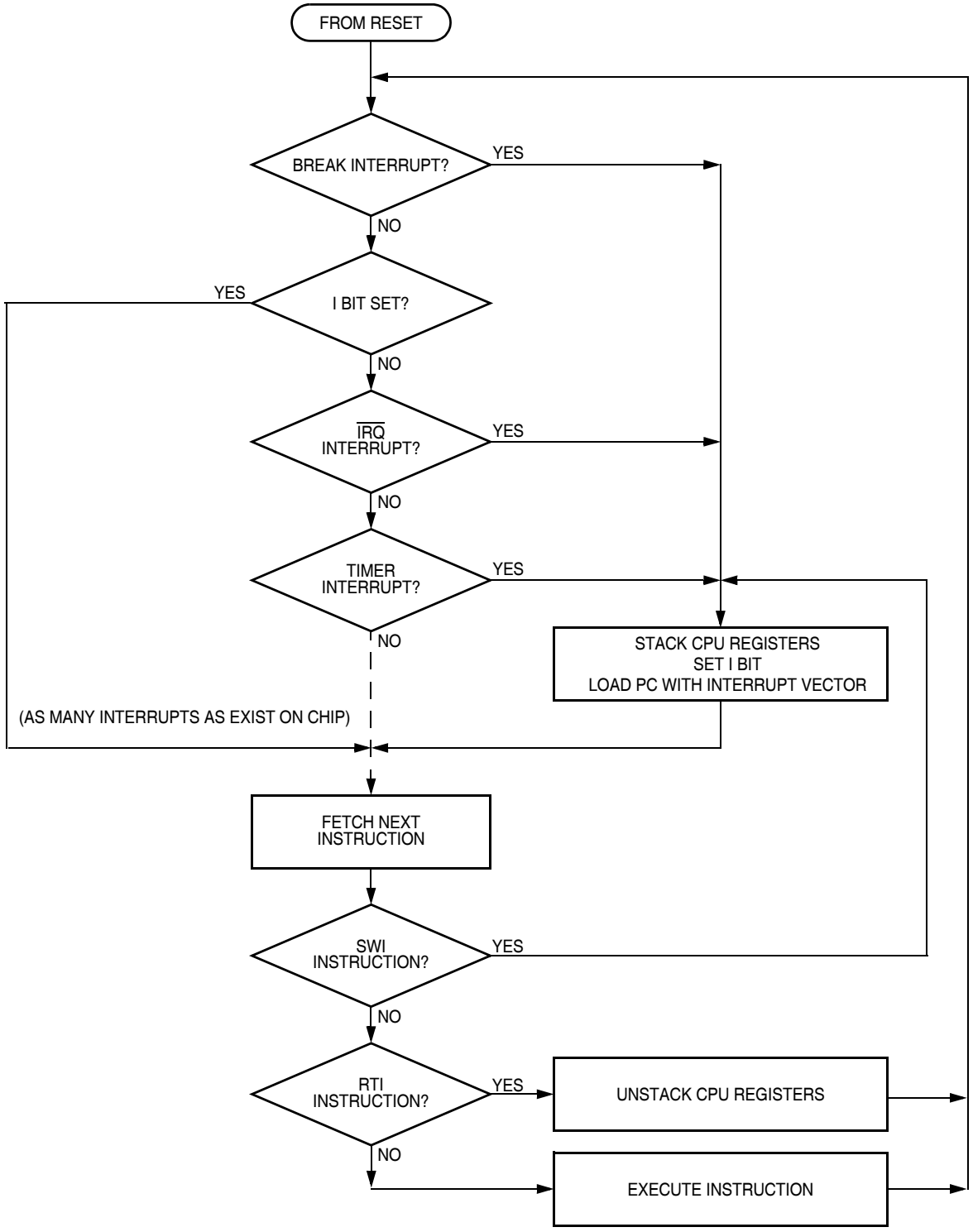
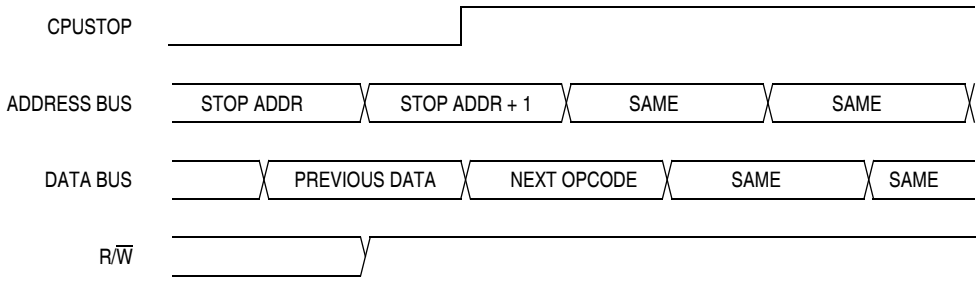


Figure 13-7. Interrupt Processing

The SIM counter is held in reset from the execution of the STOP instruction until the beginning of stop recovery. It is then used to time the recovery period. Figure 13-17 shows stop mode entry timing and Figure 13-18 shows the stop mode recovery time from interrupt or break.

NOTE

To minimize stop current, all pins configured as inputs should be driven to a logic 1 or logic 0.



NOTE: Previous data can be operand data or the STOP opcode, depending on the last instruction.

Figure 13-17. Stop Mode Entry Timing

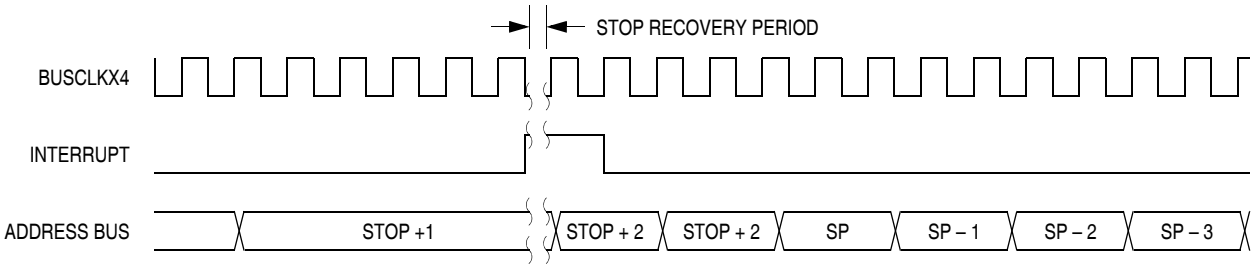


Figure 13-18. Stop Mode Recovery from Interrupt

13.8 SIM Registers

The SIM has three memory mapped registers. Table 13-4 shows the mapping of these registers.

Table 13-4. SIM Registers

Address	Register	Access Mode
$FE00	BSR	User
$FE01	SRSR	User
$FE03	BFCR	User

When ELSxB:A = 00, this read/write bit selects the initial output level of the TCHx pin (see Table 14-3). Reset clears the MSxA bit.

1 = Initial output level low
0 = Initial output level high

NOTE

Before changing a channel function by writing to the MSxB or MSxA bit, set the TSTOP and TRST bits in the TIM status and control register (TSC).

Table 14-3. Mode, Edge, and Level Selection

MSxB	MSxA	ELSxB	ELSxA	Mode	Configuration
X	0	0	0	Output preset	Pin under port control; initial output level high
X	1	0	0		Pin under port control; initial output level low
0	0	0	1	Input capture	Capture on rising edge only
0	0	1	0		Capture on falling edge only
0	0	1	1		Capture on rising or falling edge
0	1	0	0	Output compare or PWM	Software compare only
0	1	0	1		Toggle output on compare
0	1	1	0		Clear output on compare
0	1	1	1		Set output on compare
1	X	0	1	Buffered output compare or buffered PWM	Toggle output on compare
1	X	1	0		Clear output on compare
1	X	1	1		Set output on compare

ELSxB and ELSxA — Edge/Level Select Bits

When channel x is an input capture channel, these read/write bits control the active edge-sensing logic on channel x.

When channel x is an output compare channel, ELSxB and ELSxA control the channel x output behavior when an output compare occurs.

When ELSxB and ELSxA are both clear, channel x is not connected to an I/O port, and pin TCHx is available as a general-purpose I/O pin. Table 14-3 shows how ELSxB and ELSxA work. Reset clears the ELSxB and ELSxA bits.

NOTE

After initially enabling a TIM channel register for input capture operation and selecting the edge sensitivity, clear CHxF to ignore any erroneous edge detection flags.

TOVx — Toggle-On-Overflow Bit

When channel x is an output compare channel, this read/write bit controls the behavior of the channel x output when the TIM counter overflows. When channel x is an input capture channel, TOVx has no effect Reset clears the TOVx bit.

1 = Channel x pin toggles on TIM counter overflow.
0 = Channel x pin does not toggle on TIM counter overflow.

NOTE

When TOVx is set, a TIM counter overflow takes precedence over a channel x output compare if both occur at the same time.

Table 15-7. READSP (Read Stack Pointer) Command

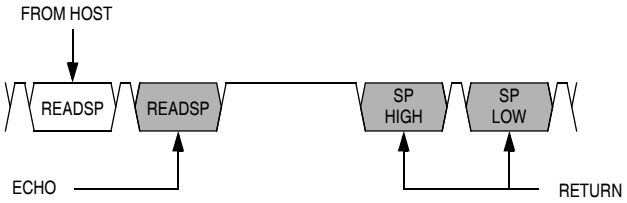
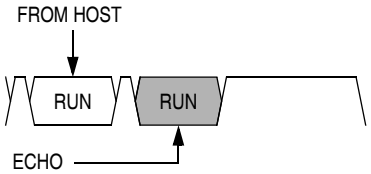
Description	Reads stack pointer
Operand	None
Data Returned	Returns incremented stack pointer value (SP + 1) in high-byte:low-byte order
Opcode	$0C
Command Sequence	

Table 15-8. RUN (Run User Program) Command

Description	Executes PULH and RTI instructions
Operand	None
Data Returned	None
Opcode	$28
Command Sequence	

The MCU executes the SWI and PSHH instructions when it enters monitor mode. The RUN command tells the MCU to execute the PULH and RTI instructions. Before sending the RUN command, the host can modify the stacked CPU registers to prepare to run the host program. The READSP command returns the incremented stack pointer value, SP + 1. The high and low bytes of the program counter are at addresses SP + 5 and SP + 6.

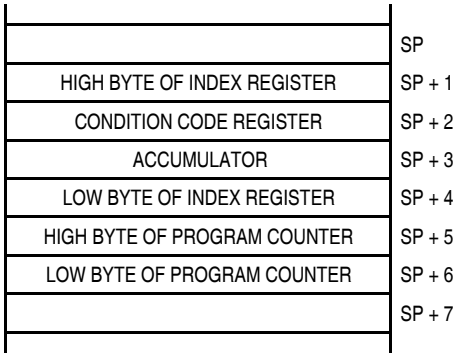


Figure 15-17. Stack Pointer at Monitor Mode Entry

16.5 5-V DC Electrical Characteristics

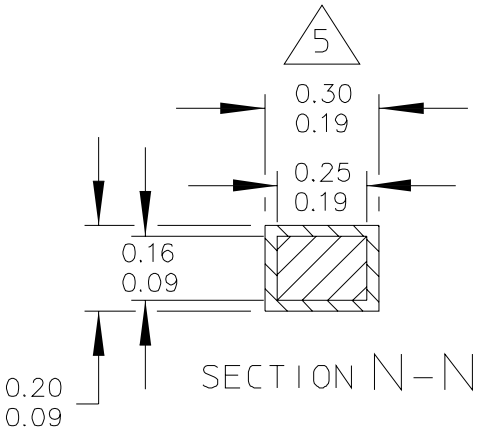
Characteristic[1]	Symbol	Min	Typ[2]	Max	Unit
Output high voltage I_{Load} = –2.0 mA, all I/O pins I_{Load} = –10.0 mA, all I/O pins I_{Load} = –15.0 mA, PTA0, PTA1, PTA3–PTA5 only	V_{OH}	 V_{DD}–0.4 V_{DD}–1.5 V_{DD}–0.8	 — — —	 — — —	V
Maximum combined I_{OH} (all I/O pins)	I_{OHT}	—	—	50	mA
Output low voltage I_{Load} = 1.6 mA, all I/O pins I_{Load} = 10.0 mA, all I/O pins I_{Load} = 15.0 mA, PTA0, PTA1, PTA3–PTA5 only	V_{OL}	 — — —	 — — —	 0.4 1.5 0.8	V
Maximum combined I_{OL} (all I/O pins)	I_{OLT}	—	—	50	mA
Input high voltage PTA0–PTA5, PTB0–PTB7	V_{IH}	0.7 x V_{DD}	—	V_{DD}	V
Input low voltage PTA0–PTA5, PTB0–PTB7	V_{IL}	V_{SS}	—	0.3 x V_{DD}	V
Input hysteresis	V_{HYS}	0.06 x V_{DD}	—	—	V
DC injection current, all ports	I_{INJ}	–2	—	+2	mA
Total dc current injection (sum of all I/O)	I_{INJTOT}	–25	—	+25	mA
Ports Hi-Z leakage current	I_{IL}	–1	±0.1	+1	µA
Capacitance Ports (as input) Ports (as input)	 C_{IN} C_{OUT}	 — —	 — —	 12 8	pF
POR rearm voltage[3]	V_{POR}	0	—	100	mV
POR rise time ramp rate[4]	R_{POR}	0.035	—	—	V/ms
Monitor mode entry voltage	V_{TST}	V_{DD} + 2.5	—	9.1	V
Pullup resistors[5] PTA0–PTA5, PTB0–PTB7	R_{PU}	16	26	36	kΩ
Low-voltage inhibit reset, trip falling voltage	V_{TRIPF}	3.90	4.20	4.50	V
Low-voltage inhibit reset, trip rising voltage	V_{TRIPR}	4.00	4.30	4.60	V
Low-voltage inhibit reset/recover hysteresis	V_{HYS}	—	100	—	mV

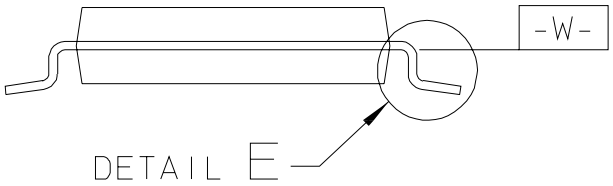
1. V_{DD} = 4.5 to 5.5 Vdc, V_{SS} = 0 Vdc, T_A = T_L to T_H, unless otherwise noted.
2. Typical values reflect average measurements at midpoint of voltage range, 25•C only.
3. Maximum is highest voltage that POR is guaranteed.
4. If minimum V_{DD} is not reached before the internal POR reset is released, the LVI will hold the part in reset until minimum V_{DD} is reached.
5. R_{PU} is measured at V_{DD} = 5.0 V.

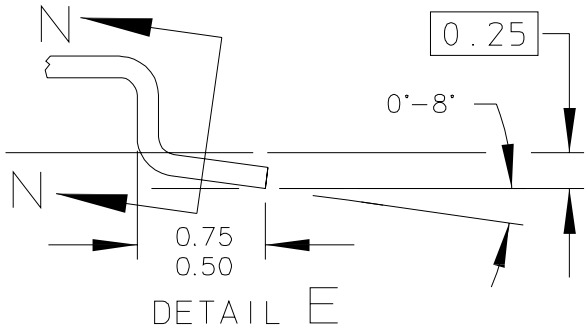
16.16 Memory Characteristics

Characteristic	Symbol	Min	Typ	Max	Unit
RAM data retention voltage	V_{RDR}	1.3	—	—	V
FLASH program bus clock frequency	—	1	—	—	MHz
FLASH read bus clock frequency	f_{Read}(1)	0	—	8 M	Hz
FLASH page erase time <1 k cycles >1 k cycles	t_{Erase}	 0.9 3.6	 1 4	 1.1 5.5	ms
FLASH mass erase time	t_{MErase}	4	—	—	ms
FLASH PGM/ERASE to HVEN setup time	t_{NVS}	10	—	—	µs
FLASH high-voltage hold time	t_{NVH}	5	—	—	µs
FLASH high-voltage hold time (mass erase)	t_{NVHL}	100	—	—	µs
FLASH program hold time	t_{PGS}	5	—	—	µs
FLASH program time	t_{PROG}	30	—	40	µs
FLASH return to read time	t_{RCV}(2)	1	—	—	µs
FLASH cumulative program HV period	t_{HV}(3)	—	—	4	ms
FLASH endurance(4)	—	10 k	100 k	—	Cycles
FLASH data retention time(5)	—	15	100	—	Years

1. f_{Read} is defined as the frequency range for which the FLASH memory can be read.
2. t_{RCV} is defined as the time it needs before the FLASH can be read after turning off the high voltage charge pump, by clearing HVEN to 0.
3. t_{HV} is defined as the cumulative high voltage programming time to the same row before next erase. t_{HV} must satisfy this condition: $t_{NVS} + t_{NVH} + t_{PGS} + (t_{PROG} \times 32) \leq t_{HV}$ maximum.
4. Typical endurance was evaluated for this product family. For additional information on how Freescale defines *Typical Endurance*, please refer to Engineering Bulletin EB619.
5. Typical data retention values are based on intrinsic capability of the technology measured at high temperature and de-rated to 25•C using the Arrhenius equation. For additional information on how Freescale defines *Typical Data Retention*, please refer to Engineering Bulletin EB618.







TITLE:

16 LD TSSOP, PITCH 0.65MM

CASE NUMBER: 948F-01

STANDARD: JEDEC

PACKAGE CODE: 6117